

AMENDMENTS TO THE CLAIMS

Claims 1-36 (Canceled)

37. (New) An antenna comprising:
an element; and wherein
the element is formed from conductor patterns on a plurality of layers including at least one buried layer of a multilayer PCB, and the conductor patterns are in stacked relation and interconnected through the PCB.
38. (New) An antenna according to claim 37, wherein the PCB is apertured adjacent to the element.
39. (New) An antenna according to claim 37, including an antenna ground plane comprising a plurality of vias connecting ground plane regions on respective PCB layers.
40. (New) An antenna according to claim 39, wherein the PCB is apertured adjacent to the element.
41. (New) An antenna in accordance with claim 37 wherein interconnection of the conductor patterns is from the conductor patterns through the at least one buried layer.
42. (New) An antenna in accordance with claim 41 wherein the interconnection is by vias extending through the at least one buried layer of the PCB.
43. (New) A mobile phone including an antenna comprising an element formed from conductor patterns on a plurality of layers including at least one buried layer of a

multilayer PCB, wherein the conductor patterns are in stacked relation and interconnected through the PCB.

44. (New) A mobile phone according to claim 43, wherein the PCB is apertured adjacent to the element.
45. (New) A mobile phone according to claim 43, including an antenna ground plane comprising a plurality of vias connecting ground plane regions on respective PCB layers.
46. (New) A mobile phone according to claim 45, wherein the PCB is apertured adjacent to the element.
47. (New) A mobile phone in accordance with claim 43 wherein interconnection of the conductor patterns is from the conductor patterns through the at least one buried layer.
48. (New) A mobile phone in accordance with claim 47 wherein the interconnection is by vias extending through the at least one buried layer of the PCB.